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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	132
Number of Logic Elements/Cells	1320
Total RAM Bits	-
Number of I/O	199
Number of Gates	16000
Voltage - Supply	4.75V ~ 5.25V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	240-BFQFP
Supplier Device Package	240-PQFP (32x32)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epf6016qi240-3

...and More Features

- Powerful I/O pins
  - Individual tri-state output enable control for each pin
  - Programmable output slew-rate control to reduce switching noise
  - Fast path from register to I/O pin for fast clock-to-output time
- Flexible interconnect
  - FastTrack® Interconnect continuous routing structure for fast, predictable interconnect delays
  - Dedicated carry chain that implements arithmetic functions such as fast adders, counters, and comparators (automatically used by software tools and megafunctions)
  - Dedicated cascade chain that implements high-speed, high-fan-in logic functions (automatically used by software tools and megafunctions)
  - Tri-state emulation that implements internal tri-state networks
  - Four low-skew global paths for clock, clear, preset, or logic signals
- Software design support and automatic place-and-route provided by Altera's development system for Windows-based PCs, Sun SPARCstations, and HP 9000 Series 700/800
- Flexible package options
  - Available in a variety of packages with 100 to 256 pins, including the innovative FineLine BGA™ packages (see Table 2)
  - SameFrame™ pin-compatibility (with other FLEX® 6000 devices) across device densities and pin counts
  - Thin quad flat pack (TQFP), plastic quad flat pack (PQFP), and ball-grid array (BGA) packages (see Table 2)
  - Footprint- and pin-compatibility with other FLEX 6000 devices in the same package
- Additional design entry and simulation support provided by EDIF 2 0 0 and 3 0 0 netlist files, the library of parameterized modules (LPM), Verilog HDL, VHDL, DesignWare components, and other interfaces to popular EDA tools from manufacturers such as Cadence, Exemplar Logic, Mentor Graphics, OrCAD, Synopsys, Synplicity, VeriBest, and Viewlogic

Table 2. FLEX 6000 Package Options & I/O Pin Count

Device	100-Pin TQFP	100-Pin FineLine BGA	144-Pin TQFP	208-Pin PQFP	240-Pin PQFP	256-Pin BGA	256-pin FineLine BGA
EPF6010A	71		102				
EPF6016			117	171	199	204	
EPF6016A	81	81	117	171			171
EPF6024A			117	171	199	218	219

General Description

The Altera® FLEX 6000 programmable logic device (PLD) family provides a low-cost alternative to high-volume gate array designs. FLEX 6000 devices are based on the OptiFLEX architecture, which minimizes die size while maintaining high performance and routability. The devices have reconfigurable SRAM elements, which give designers the flexibility to quickly change their designs during prototyping and design testing. Designers can also change functionality during operation via in-circuit reconfiguration.

FLEX 6000 devices are reprogrammable, and they are 100% tested prior to shipment. As a result, designers are not required to generate test vectors for fault coverage purposes, allowing them to focus on simulation and design verification. In addition, the designer does not need to manage inventories of different gate array designs. FLEX 6000 devices are configured on the board for the specific functionality required.

Table 3 shows FLEX 6000 performance for some common designs. All performance values shown were obtained using Synopsys DesignWare or LPM functions. Special design techniques are not required to implement the applications; the designer simply infers or instantiates a function in a Verilog HDL, VHDL, Altera Hardware Description Language (AHDL), or schematic design file.

Table 3. FLEX 6000 Device Performance for Common Designs

Application	LEs Used	Performance			Units
		-1 Speed Grade	-2 Speed Grade	-3 Speed Grade	
16-bit loadable counter	16	172	153	133	MHz
16-bit accumulator	16	172	153	133	MHz
24-bit accumulator	24	136	123	108	MHz
16-to-1 multiplexer (pin-to-pin) *(1)*	10	12.1	13.4	16.6	ns
16 × 16 multiplier with a 4-stage pipeline	592	84	67	58	MHz

Note:
(1) This performance value is measured as a pin-to-pin delay.

Functional Description

The FLEX 6000 OptiFLEX architecture consists of logic elements (LEs). Each LE includes a 4-input look-up table (LUT), which can implement any 4-input function, a register, and dedicated paths for carry and cascade chain functions. Because each LE contains a register, a design can be easily pipelined without consuming more LEs. The specified gate count for FLEX 6000 devices includes all LUTs and registers.

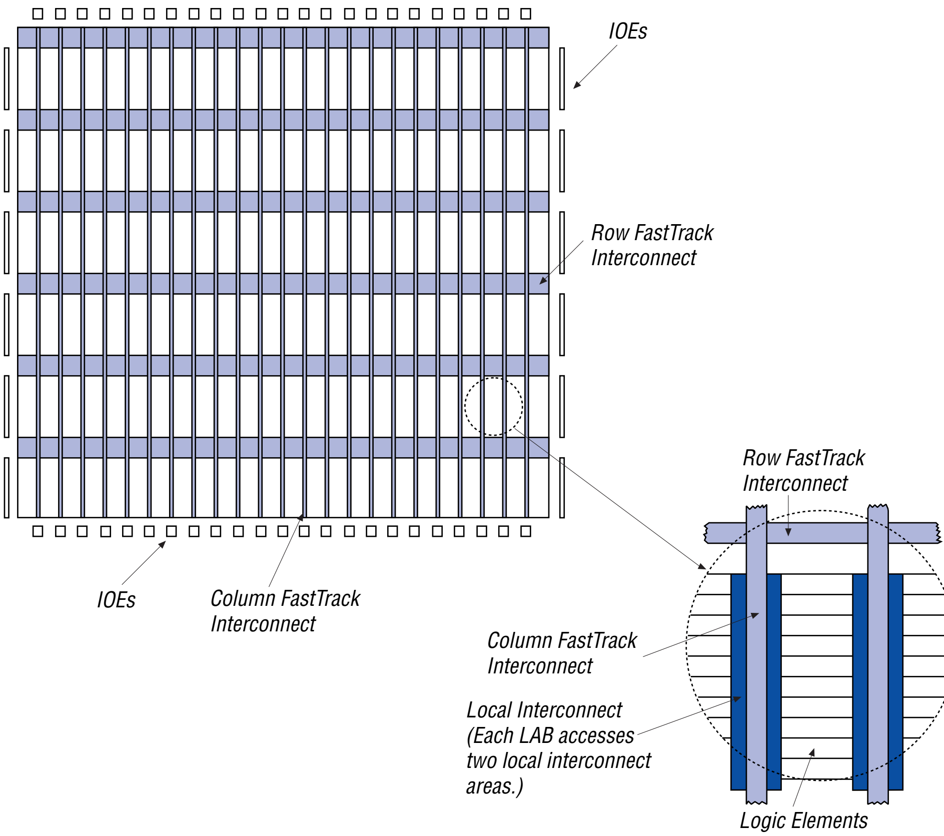
LEs are combined into groups called logic array blocks (LABs); each LAB contains 10 LEs. The Altera software automatically places related LEs into the same LAB, minimizing the number of required interconnects. Each LAB can implement a medium-sized block of logic, such as a counter or multiplexer.

Signal interconnections within FLEX 6000 devices—and to and from device pins—are provided via the routing structure of the FastTrack Interconnect. The routing structure is a series of fast, continuous row and column channels that run the entire length and width of the device. Any LE or pin can feed or be fed by any other LE or pin via the FastTrack Interconnect. See “FastTrack Interconnect” on page 17 of this data sheet for more information.

Each I/O pin is fed by an I/O element (IOE) located at the end of each row and column of the FastTrack Interconnect. Each IOE contains a bidirectional I/O buffer. Each IOE is placed next to an LAB, where it can be driven by the local interconnect of that LAB. This feature allows fast clock-to-output times of less than 8 ns when a pin is driven by any of the 10 LEs in the adjacent LAB. Also, any LE can drive any pin via the row and column interconnect. I/O pins can drive the LE registers via the row and column interconnect, providing setup times as low as 2 ns and hold times of 0 ns. IOEs provide a variety of features, such as JTAG BST support, slew-rate control, and tri-state buffers.

Figure 1 shows a block diagram of the FLEX 6000 OptiFLEX architecture. Each group of ten LEs is combined into an LAB, and the LABs are arranged into rows and columns. The LABs are interconnected by the FastTrack Interconnect. IOEs are located at the end of each FastTrack Interconnect row and column.

Figure 1. OptiFLEX Architecture Block Diagram

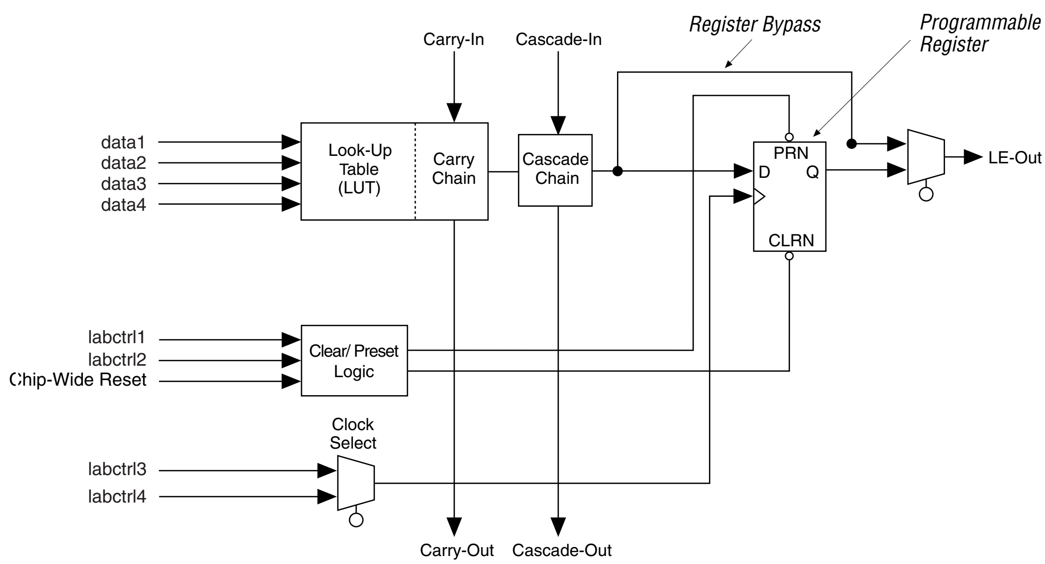


FLEX 6000 devices provide four dedicated, global inputs that drive the control inputs of the flipflops to ensure efficient distribution of high-speed, low-skew control signals. These inputs use dedicated routing channels that provide shorter delays and lower skews than the FastTrack Interconnect. These inputs can also be driven by internal logic, providing an ideal solution for a clock divider or an internally generated asynchronous clear signal that clears many registers in the device. The dedicated global routing structure is built into the device, eliminating the need to create a clock tree.

Logic Array Block

An LAB consists of ten LEs, their associated carry and cascade chains, the LAB control signals, and the LAB local interconnect. The LAB provides the coarse-grained structure of the FLEX 6000 architecture, and facilitates efficient routing with optimum device utilization and high performance.

Figure 4. Logic Element



The programmable flipflop in the LE can be configured for D, T, JK, or SR operation. The clock and clear control signals on the flipflop can be driven by global signals, general-purpose I/O pins, or any internal logic. For combinatorial functions, the flipflop is bypassed and the output of the LUT drives the outputs of the LE. The LE output can drive both the local interconnect and the FastTrack Interconnect.

The FLEX 6000 architecture provides two types of dedicated high-speed data paths that connect adjacent LEs without using local interconnect paths: carry chains and cascade chains. A carry chain supports high-speed arithmetic functions such as counters and adders, while a cascade chain implements wide-input functions such as equivalent comparators with minimum delay. Carry and cascade chains connect LEs 2 through 10 in an LAB and all LABs in the same half of the row. Because extensive use of carry and cascade chains can reduce routing flexibility, these chains should be limited to speed-critical portions of a design.

Carry Chain

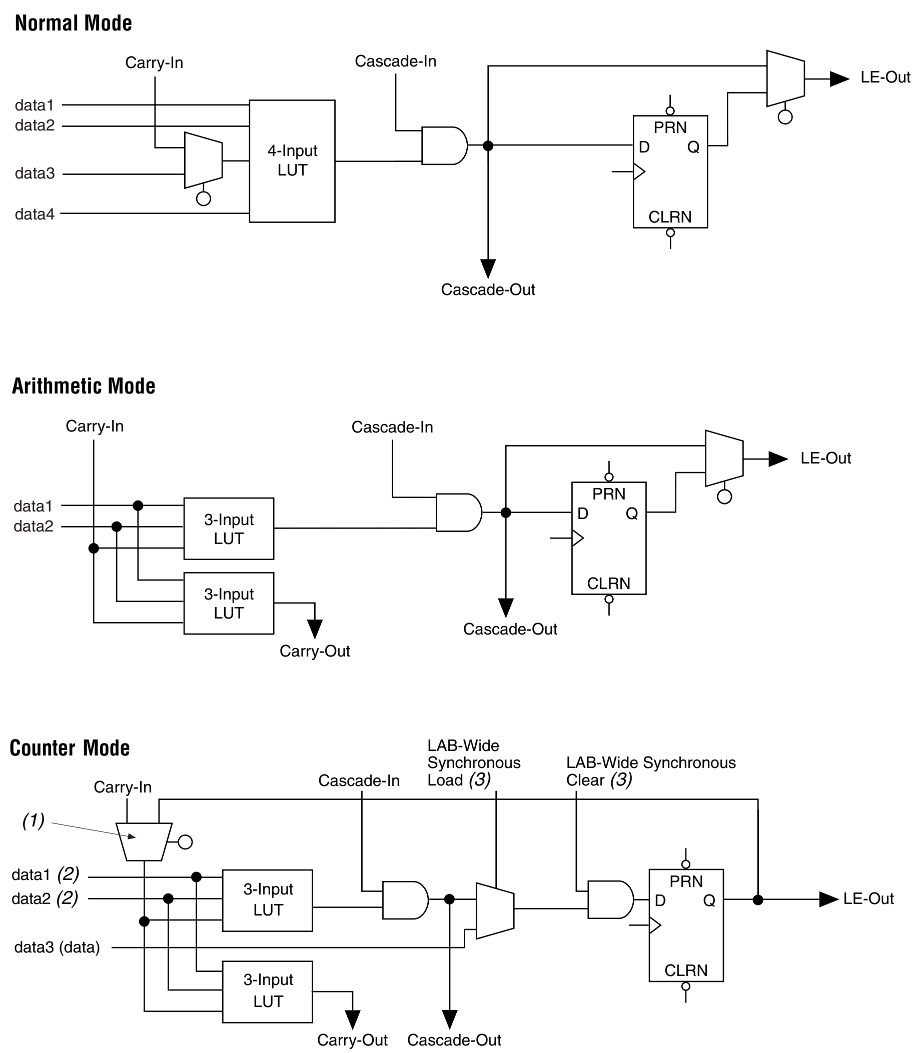
The carry chain provides a very fast (0.1 ns) carry-forward function between LEs. The carry-in signal from a lower-order bit drives forward into the higher-order bit via the carry chain, and feeds into both the LUT and the next portion of the carry chain. This feature allows the FLEX 6000 architecture to implement high-speed counters, adders, and comparators of arbitrary width. Carry chain logic can be created automatically by the Altera software during design processing, or manually by the designer during design entry. Parameterized functions such as LPM and DesignWare functions automatically take advantage of carry chains for the appropriate functions.

Because the first LE of each LAB can generate control signals for that LAB, the first LE in each LAB is not included in carry chains. In addition, the inputs of the first LE in each LAB may be used to generate synchronous clear and load enable signals for counters implemented with carry chains.

Carry chains longer than nine LEs are implemented automatically by linking LABs together. For enhanced fitting, a long carry chain skips alternate LABs in a row. A carry chain longer than one LAB skips either from an even-numbered LAB to another even-numbered LAB, or from an odd-numbered LAB to another odd-numbered LAB. For example, the last LE of the first LAB in a row carries to the second LE of the third LAB in the row. In addition, the carry chain does not cross the middle of the row. For instance, in the EPF6016 device, the carry chain stops at the 11th LAB in a row and a new carry chain begins at the 12th LAB.

Figure 5 shows how an n-bit full adder can be implemented in $n + 1$ LEs with the carry chain. One portion of the LUT generates the sum of two bits using the input signals and the carry-in signal; the sum is routed to the output of the LE. Although the register can be bypassed for simple adders, it can be used for an accumulator function. Another portion of the LUT and the carry chain logic generates the carry-out signal, which is routed directly to the carry-in signal of the next-higher-order bit. The final carry-out signal is routed to an LE, where it is driven onto the FastTrack Interconnect.

Figure 7. LE Operating Modes



Notes:
(1) The register feedback multiplexer is available on LE 2 of each LAB.
(2) The `data1` and `data2` input signals can supply a clock enable, up or down control, or register feedback signals for all LEs other than the second LE in an LAB.
(3) The LAB-wide synchronous clear and LAB-wide synchronous load affect all registers in an LAB.

Normal Mode

The normal mode is suitable for general logic applications, combinatorial functions, or wide decoding functions that can take advantage of a cascade chain. In normal mode, four data inputs from the LAB local interconnect and the carry-in are inputs to a 4-input LUT. The Altera software automatically selects the carry-in or the DATA3 signal as one of the inputs to the LUT. The LUT output can be combined with the cascade-in signal to form a cascade chain through the cascade-out signal.

Arithmetic Mode

The arithmetic mode is ideal for implementing adders, accumulators, and comparators. An LE in arithmetic mode uses two 3-input LUTs. One LUT computes a 3-input function; the other generates a carry output. As shown in Figure 7, the first LUT uses the carry-in signal and two data inputs from the LAB local interconnect to generate a combinatorial or registered output. For example, when implementing an adder, this output is the sum of three signals: DATA1, DATA2, and carry-in. The second LUT uses the same three signals to generate a carry-out signal, thereby creating a carry chain. The arithmetic mode also supports simultaneous use of the cascade chain.

The Altera software implements logic functions to use the arithmetic mode automatically where appropriate; the designer does not have to decide how the carry chain will be used.

Counter Mode

The counter mode offers counter enable, synchronous up/down control, synchronous clear, and synchronous load options. The counter enable and synchronous up/down control signals are generated from the data inputs of the LAB local interconnect. The synchronous clear and synchronous load options are LAB-wide signals that affect all registers in the LAB. Consequently, if any of the LEs in a LAB use counter mode, other LEs in that LAB must be used as part of the same counter or be used for a combinatorial function. In addition, the Altera software automatically places registers that are not in the counter into other LABs.

The counter mode uses two 3-input LUTs: one generates the counter data and the other generates the fast carry bit. A 2-to-1 multiplexer provides synchronous loading, and another AND gate provides synchronous clearing. If the cascade function is used by an LE in counter mode, the synchronous clear or load will override any signal carried on the cascade chain. The synchronous clear overrides the synchronous load.

A row channel can be driven by an LE or by one of two column channels. These three signals feed a 3-to-1 multiplexer that connects to six specific row channels. Row channels drive into the local interconnect via multiplexers.

Each column of LABs is served by a dedicated column interconnect. The LEs in an LAB can drive the column interconnect. The LEs in an LAB, a column IOE, or a row interconnect can drive the column interconnect. The column interconnect can then drive another row's interconnect to route the signals to other LABs in the device. A signal from the column interconnect must be routed to the row interconnect before it can enter an LAB.

Each LE has a FastTrack Interconnect output and a local output. The FastTrack interconnect output can drive six row and two column lines directly; the local output drives the local interconnect. Each local interconnect channel driven by an LE can drive four row and two column channels. This feature provides additional flexibility, because each LE can drive any of ten row lines and four column lines.

In addition, LEs can drive global control signals. This feature is useful for distributing internally generated clock, asynchronous clear, and asynchronous preset signals. A pin-driven global signal can also drive data signals, which is useful for high-fan-out data signals.

Each LAB drives two groups of local interconnects, which allows an LE to drive two LABs, or 20 LEs, via the local interconnect. The row-to-local multiplexers are used more efficiently, because the multiplexers can now drive two LABs. Figure 10 shows how an LAB connects to row and column interconnects.

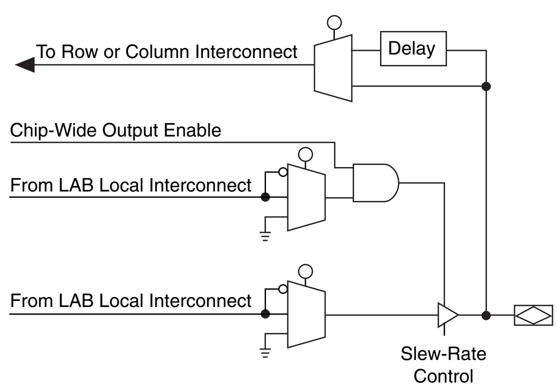
I/O Elements

An IOE contains a bidirectional I/O buffer and a tri-state buffer. IOEs can be used as input, output, or bidirectional pins. An IOE receives its data signals from the adjacent local interconnect, which can be driven by a row or column interconnect (allowing any LE in the device to drive the IOE) or by an adjacent LE (allowing fast clock-to-output delays). A FastFLEX™ I/O pin is a row or column output pin that receives its data signals from the adjacent local interconnect driven by an adjacent LE. The IOE receives its output enable signal through the same path, allowing individual output enables for every pin and permitting emulation of open-drain buffers. The Altera Compiler uses programmable inversion to invert the data or output enable signals automatically where appropriate. Open-drain emulation is provided by driving the data input low and toggling the OE of each IOE. This emulation is possible because there is one OE per pin.

A chip-wide output enable feature allows the designer to disable all pins of the device by asserting one pin (`DEV_OE`). This feature is useful during board debugging or testing.

Figure 12 shows the IOE block diagram.

Figure 12. IOE Block Diagram



MultiVolt I/O Interface

The FLEX 6000 device architecture supports the MultiVolt I/O interface feature, which allows FLEX 6000 devices to interface with systems of differing supply voltages. The EPF6016 device can be set for 3.3-V or 5.0-V I/O pin operation. This device has one set of V_{CC} pins for internal operation and input buffers (VCCINT), and another set for output drivers (VCCIO).

The VCCINT pins on 5.0-V FLEX 6000 devices must always be connected to a 5.0-V power supply. With a 5.0-V V_{CCINT} level, input voltages are at TTL levels and are therefore compatible with 3.3-V and 5.0-V inputs.

The VCCIO pins on 5.0-V FLEX 6000 devices can be connected to either a 3.3-V or 5.0-V power supply, depending on the output requirements. When the VCCIO pins are connected to a 5.0-V power supply, the output levels are compatible with 5.0-V systems. When the VCCIO pins are connected to a 3.3-V power supply, the output high is 3.3 V and is therefore compatible with 3.3-V or 5.0-V systems. Devices operating with V_{CCIO} levels lower than 4.75 V incur a nominally greater timing delay of t_{OD2} instead of t_{OD1}.

On 3.3-V FLEX 6000 devices, the VCCINT pins must be connected to a 3.3-V power supply. Additionally, 3.3-V FLEX 6000A devices can interface with 2.5-V, 3.3-V, or 5.0-V systems when the VCCIO pins are tied to 2.5 V. The output can drive 2.5-V systems, and the inputs can be driven by 2.5-V, 3.3-V, or 5.0-V systems. When the VCCIO pins are tied to 3.3 V, the output can drive 3.3-V or 5.0-V systems. MultiVolt I/Os are not supported on 100-pin TQFP or 100-pin FineLine BGA packages.

Table 7 describes FLEX 6000 MultiVolt I/O support.

Table 7. FLEX 6000 MultiVolt I/O Support

V_{CCINT} (V)	V_{CCIO} (V)	Input Signal (V)			Output Signal (V)		
		2.5	3.3	5.0	2.5	3.3	5.0
3.3	2.5	v	v	v	v		
3.3	3.3	v	v	v	v *(1)*	v	v
5.0	3.3		v	v		v	v
5.0	5.0		v	v			v

Note:
(1) When V_{CCIO} = 3.3 V, a FLEX 6000 device can drive a 2.5-V device that has 3.3-V tolerant inputs.

Open-drain output pins on 5.0-V or 3.3-V FLEX 6000 devices (with a pull-up resistor to the 5.0-V supply) can drive 5.0-V CMOS input pins that require a V_{IH} of 3.5 V. When the open-drain pin is active, it will drive low. When the pin is inactive, the trace will be pulled up to 5.0 V by the resistor. The open-drain pin will only drive low or tri-state; it will never drive high. The rise time is dependent on the value of the pull-up resistor and load impedance. The I_{OL} current specification should be considered when selecting a pull-up resistor.

Output pins on 5.0-V FLEX 6000 devices with V_{CCIO} = 3.3 V or 5.0 V (with a pull-up resistor to the 5.0-V supply) can also drive 5.0-V CMOS input pins. In this case, the pull-up transistor will turn off when the pin voltage exceeds 3.3 V. Therefore, the pin does not have to be open-drain.

Power Sequencing & Hot-Socketing

Because FLEX 6000 family devices can be used in a mixed-voltage environment, they have been designed specifically to tolerate any possible power-up sequence. The V_{CCIO} and V_{CCINT} power planes can be powered in any order.

Signals can be driven into 3.3-V FLEX 6000 devices before and during power up without damaging the device. Additionally, FLEX 6000 devices do not drive out during power up. Once operating conditions are reached, FLEX 6000 devices operate as specified by the user.

IEEE Std. 1149.1 (JTAG) Boundary-Scan Support

All FLEX 6000 devices provide JTAG BST circuitry that comply with the IEEE Std. 1149.1-1990 specification. Table 8 shows JTAG instructions for FLEX 6000 devices. JTAG BST can be performed before or after configuration, but not during configuration (except when you disable JTAG support in user mode).

1 See *Application Note 39 (IEEE 1149.1 (JTAG) Boundary-Scan Testing in Altera Devices)* for more information on JTAG BST circuitry.

Table 8. FLEX 6000 JTAG Instructions

JTAG Instruction	Description
SAMPLE/PRELOAD	Allows a snapshot of the signals at the device pins to be captured and examined during normal device operation, and permits an initial data pattern to be output at the device pins.
EXTEST	Allows the external circuitry and board-level interconnections to be tested by forcing a test pattern at the output pins and capturing test result at the input pins.
BYPASS	Places the 1-bit bypass register between the `TDI` and `TDO` pins, which allows the BST data to pass synchronously through the selected device to adjacent devices during normal device operation.

Table 10. JTAG Timing Parameters & Values

Symbol	Parameter	Min	Max	Unit
t_{JCP}	`TCK` clock period	100		ns
t_{JCH}	`TCK` clock high time	50		ns
t_{JCL}	`TCK` clock low time	50		ns
t_{JPSU}	JTAG port setup time	20		ns
t_{JPH}	JTAG port hold time	45		ns
t_{JPCO}	JTAG port clock-to-output		25	ns
t_{JPZX}	JTAG port high impedance to valid output		25	ns
t_{JPXZ}	JTAG port valid output to high impedance		25	ns
t_{JSSU}	Capture register setup time	20		ns
t_{JSH}	Capture register hold time	45		ns
t_{JSCO}	Update register clock-to-output		35	ns
t_{JSZX}	Update register high impedance to valid output		35	ns
t_{JSXZ}	Update register valid output to high impedance		35	ns

Generic Testing

Each FLEX 6000 device is functionally tested. Complete testing of each configurable SRAM bit and all logic functionality ensures 100% configuration yield. AC test measurements for FLEX 6000 devices are made under conditions equivalent to those shown in Figure 17. Multiple test patterns can be used to configure devices during all stages of the production flow.

Figure 17. AC Test Conditions

Power supply transients can affect AC measurements. Simultaneous transitions of multiple outputs should be avoided for accurate measurement. Threshold tests must not be performed under AC conditions. Large-amplitude, fast-ground-current transients normally occur as the device outputs discharge the load capacitances. When these transients flow through the parasitic inductance between the device ground pin and the test system ground, significant reductions in observable noise immunity can result. Numbers without parentheses are for 5.0-V devices or outputs. Numbers in parentheses are for 3.3-V devices or outputs. Numbers in brackets are for 2.5-V devices or outputs.

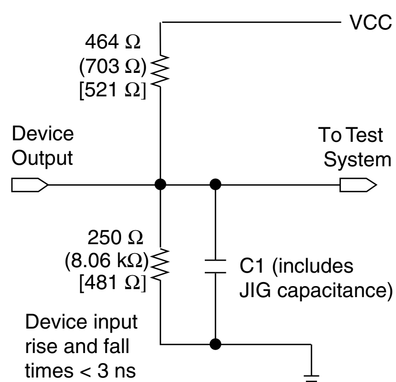


Table 33. External Timing Parameters for EPF6016 Devices					
Parameter	Speed Grade				Unit
	-2		-3		
	Min	Max	Min	Max	
t_{INSU}	3.2		4.1		ns
t_{INH}	0.0		0.0		ns
t_{OUTCO}	2.0	7.9	2.0	9.9	ns

Tables 34 through 38 show the timing information for EPF6024A devices.

Table 34. LE Timing Microparameters for EPF6024A Devices							
Parameter	Speed Grade						Unit
	-1		-2		-3		
	Min	Max	Min	Max	Min	Max	
$t_{REG\_TO\_REG}$		1.2		1.3		1.6	ns
$t_{CASC\_TO\_REG}$		0.7		0.8		1.0	ns
$t_{CARRY\_TO\_REG}$		1.6		1.8		2.2	ns
$t_{DATA\_TO\_REG}$		1.3		1.4		1.7	ns
$t_{CASC\_TO\_OUT}$		1.2		1.3		1.6	ns
$t_{CARRY\_TO\_OUT}$		2.0		2.2		2.6	ns
$t_{DATA\_TO\_OUT}$		1.8		2.1		2.6	ns
$t_{REG\_TO\_OUT}$		0.3		0.3		0.4	ns
t_{SU}	0.9		1.0		1.2		ns
t_{H}	1.3		1.4		1.7		ns
t_{CO}		0.2		0.3		0.3	ns
t_{CLR}		0.3		0.3		0.4	ns
t_{C}		1.9		2.1		2.5	ns
t_{LD_CLR}		1.9		2.1		2.5	ns
$t_{CARRY\_TO\_CARRY}$		0.2		0.2		0.3	ns
$t_{REG\_TO\_CARRY}$		1.4		1.6		1.9	ns
$t_{DATA\_TO\_CARRY}$		1.3		1.4		1.7	ns
$t_{CARRY\_TO\_CASC}$		1.1		1.2		1.4	ns
$t_{CASC\_TO\_CASC}$		0.7		0.8		1.0	ns
$t_{REG\_TO\_CASC}$		1.4		1.6		1.9	ns
$t_{DATA\_TO\_CASC}$		1.0		1.1		1.3	ns
t_{CH}	2.5		3.0		3.5		ns
t_{CL}	2.5		3.0		3.5		ns

Table 35. IOE Timing Microparameters for EPF6024A Devices							
Parameter	**Speed Grade**						**Unit**
	-1		**-2**		**-3**		
	Min	**Max**	**Min**	**Max**	**Min**	**Max**	
t_{OD1}		1.9		2.1		2.5	ns
t_{OD2}		4.0		4.4		5.3	ns
t_{OD3}		7.0		7.8		9.3	ns
t_{XZ}		4.3		4.8		5.8	ns
t_{XZ1}		4.3		4.8		5.8	ns
t_{XZ2}		6.4		7.1		8.6	ns
t_{XZ3}		9.4		10.5		12.6	ns
t_{IOE}		0.5		0.6		0.7	ns
t_{IN}		3.3		3.7		4.4	ns
t_{IN_DELAY}		5.3		5.9		7.0	ns

Table 36. Interconnect Timing Microparameters for EPF6024A Devices							
Parameter	**Speed Grade**						**Unit**
	-1		**-2**		**-3**		
	Min	**Max**	**Min**	**Max**	**Min**	**Max**	
t_{LOCAL}		0.8		0.8		1.1	ns
t_{ROW}		3.0		3.1		3.3	ns
t_{COL}		3.0		3.2		3.4	ns
t_{DIN_D}		5.4		5.6		6.2	ns
t_{DIN_C}		4.6		5.1		6.1	ns
$t_{LEGLOBAL}$		3.1		3.5		4.3	ns
$t_{LABCARRY}$		0.6		0.7		0.8	ns
$t_{LABCASC}$		0.3		0.3		0.4	ns

Table 37. External Reference Timing Parameters for EPF6024A Devices							
Parameter	**Speed Grade**						**Unit**
	-1		**-2**		**-3**		
	Min	**Max**	**Min**	**Max**	**Min**	**Max**	
t_1		45.0		50.0		60.0	ns

Table 38. External Timing Parameters for EPF6024A Devices

Parameter	Speed Grade						Unit
	-1		-2		-3		
	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.0 *(1)*		2.2 *(1)*		2.6 *(1)*		ns
t_{INH}	0.2 *(2)*		0.2 *(2)*		0.3 *(2)*		ns
t_{OUTCO}	2.0	7.4	2.0	8.2	2.0	9.9	ns

Notes:
(1) Setup times are longer when the *Increase Input Delay* option is turned on. The setup time values are shown with the *Increase Input Delay* option turned off.
(2) Hold time is zero when the *Increase Input Delay* option is turned on.

Power Consumption

The supply power (P) for FLEX 6000 devices can be calculated with the following equations:

$$P = P_{INT} + P_{IO}$$
$$P = (I_{CCSTANDBY} + I_{CCACTIVE}) \times V_{CC} + P_{IO}$$

Typical $I_{CCSTANDBY}$ values are shown as I_{CC0} in the "FLEX 6000 Device DC Operating Conditions" table on pages 31 and 33 of this data sheet. The $I_{CCACTIVE}$ value depends on the switching frequency and the application logic. This value is based on the amount of current that each LE typically consumes. The P_{IO} value, which depends on the device output load characteristics and switching frequency, can be calculated using the guidelines given in *Application Note 74 (Evaluating Power for Altera Devices)*.

The $I_{CCACTIVE}$ value can be calculated with the following equation:

$$I_{CCACTIVE} = K \times \mathbf{f_{MAX}} \times N \times \mathbf{tog_{LC}} \times \frac{\mu A}{MHz \times LE}$$

Where:
$\mathbf{f_{MAX}}$ = Maximum operating frequency in MHz
N = Total number of LEs used in a FLEX 6000 device
$\mathbf{tog_{LC}}$ = Average percentage of LEs toggling at each clock (typically 12.5%)
K = Constant, shown in Table 39

Table 39. K Constant Values

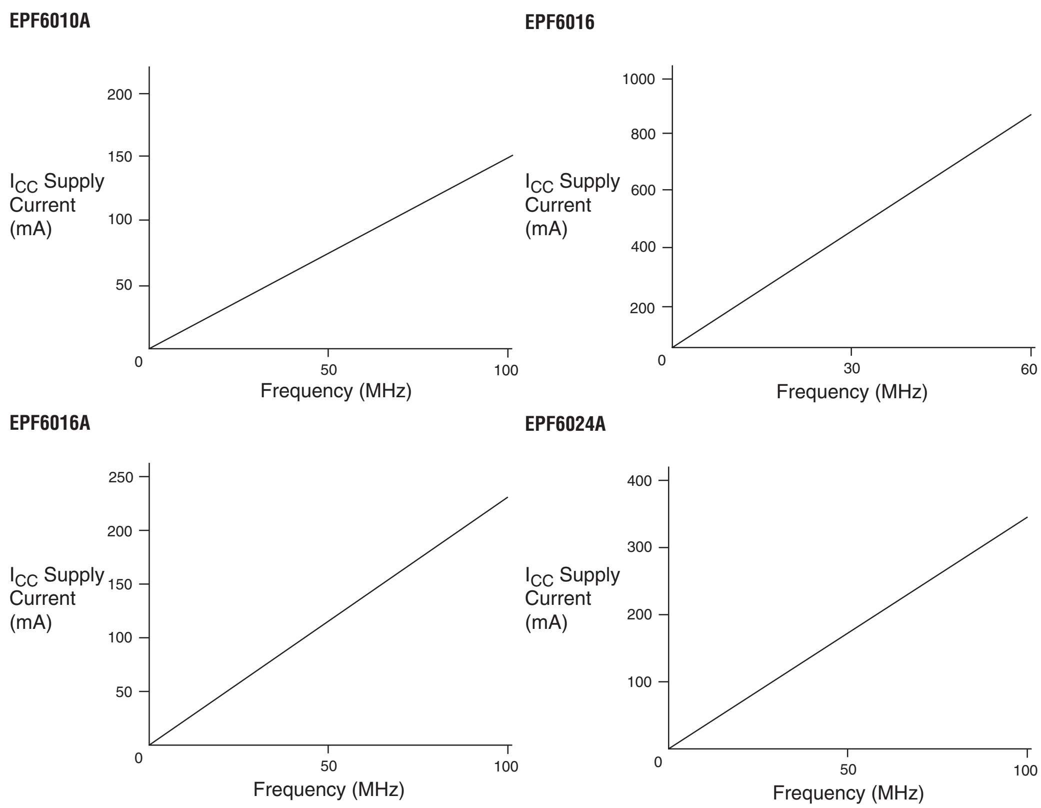
Device	K Value
EPF6010A	14
EPF6016	88
EPF6016A	14
EPF6024A	14

This calculation provides an I_{CC} estimate based on typical conditions with no output load. The actual I_{CC} should be verified during operation because this measurement is sensitive to the actual pattern in the device and the environmental operating conditions.

To better reflect actual designs, the power model (and the constant K in the power calculation equations shown above) for continuous interconnect FLEX devices assumes that LEs drive FastTrack Interconnect channels. In contrast, the power model of segmented FPGAs assumes that all LEs drive only one short interconnect segment. This assumption may lead to inaccurate results, compared to measured power consumption for an actual design in a segmented interconnect FPGA.

Figure 20 shows the relationship between the current and operating frequency for EPF6010A, EPF6016, EPF6016A, and EPF6024A devices.

Figure 20. $I_{CCACTIVE}$ vs. Operating Frequency



Device Configuration & Operation

The FLEX 6000 architecture supports several configuration schemes to load a design into the device(s) on the circuit board. This section summarizes the device operating modes and available device configuration schemes.

f See *Application Note 116 (Configuring APEX 20K, FLEX 10K & FLEX 6000 Devices)* for detailed information on configuring FLEX 6000 devices, including sample schematics, timing diagrams, configuration options, pins names, and timing parameters.

Device Pin-Outs

See the Altera web site (**http://www.altera.com**) or the *Altera Digital Library* for pin-out information.

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